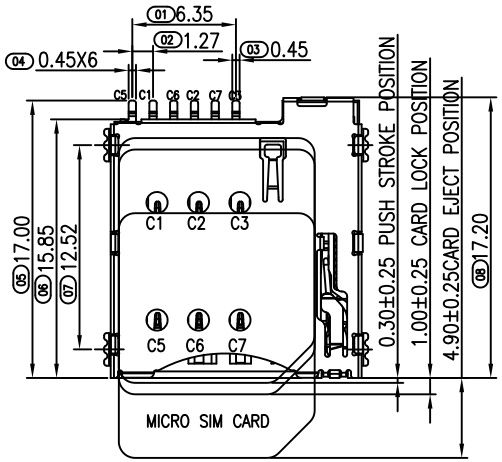

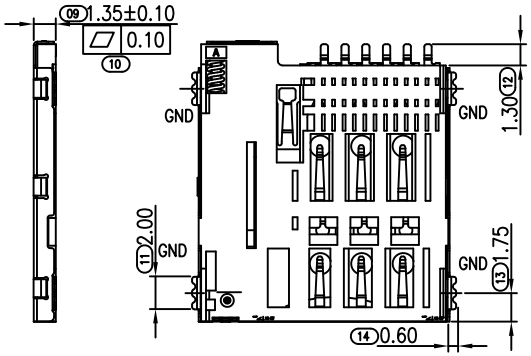

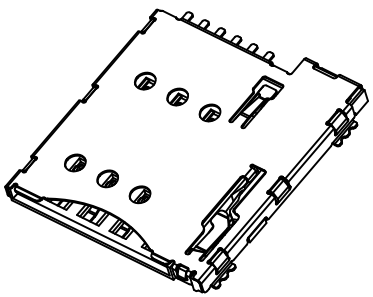

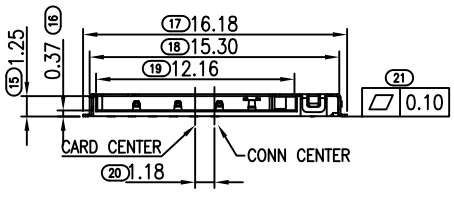

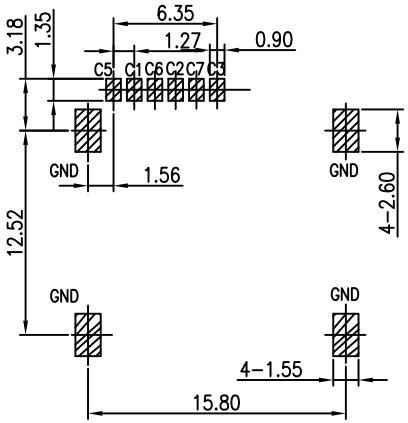

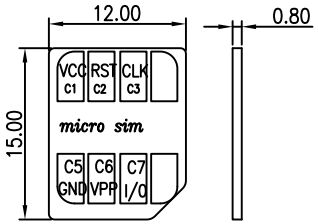

MICRO SIM CARD

■ CIRCUT TRACE KEEP OUT AREA
■ SMT SOLDER AREA

THERE SHOULD NOT BE ANY CIRCUITRIES
IN THE LAYOUT SPACE OF THE PRODUCTS.

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

NOTES:

MATERIAL:
Insulator: High Temperature Thermoplastic,
Contact: Copper Alloy
Shell: STAINLESS

PLATING:
Contact: Plated 30u" Ni Overall ,Solder Area: Tin,Contact G/F
Shell: Plated 30u" Ni Overall
Plated G/F Selective Contact Area

Electrical:
Current Rating :0.5mA max.
Voltage Rating :50V DC MAX
Ambient Temperature Range :-20°C~+85°C
Storage Temperature Range :-40°C~+70°C
Ambient Humidity Range :95% R.H. Max.
Contact Resistance:100mΩ max.
Insulation Resistance:1000M min./250V DC
Dielectric Withstanding Voltage:500V AC
Mating Cycles:5,000 Insertions
Temperature: 260°C ±5°

NO 번호	DATE 변경일자	DESCRIPTION OF REVISION 변 경 내 용	DESIGNED 작 성	CHECKED 검 토	APPROVED 승 인
DESIGNED 작성					

MATERIAL 재 질	SPECIFICATION 규 격	FINISH 표면처리	QUANTITY 수 량	SCALE 척 도 / UNIT 단위 mm

DESIGNED 작 성	CHECKED 검 토	APPROVAL 승 인	DRAWING NUMBER 도 번	
김 도 현	박 재 규	최 국 호	PART NAME 부 품 명	HY-SIM-002-P6
			MODEL NAME 제 품 명	HY-SIM-002-P6
삼현전자 주식회사			3RD ANGLE PROJ	HANYONES TECH CO.,LTD

한 유안 ELECTRONICS CO.,LTD

FILE. NO.